

## PATENT ABSTRACTS OF JAPAN

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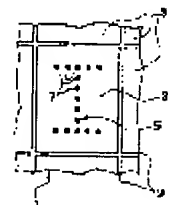
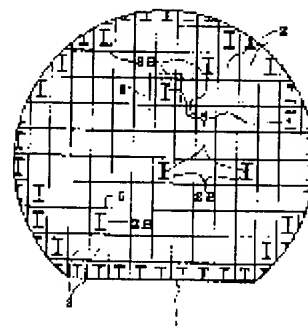
ITO TSUTOMU

## (54) IDENTIFICATION OF SEMICONDUCTOR WAFER AND SEMICONDUCTOR DEVICE

## (57)Abstract:

PURPOSE: To facilitate the recognition of good and bad articles based upon characteristic retrieval results of semiconductor device by applying a badness identification figure comprising a plurality of points to a bad semiconductor device based upon the characteristic inspection result for each semiconductor device.

CONSTITUTION: Characteristics of a plurality of semiconductor devices 3 are inspected. A failure identifying symbol 5 is formed on a failure semiconductor device 3B based upon the result of the inspection. The failure identifying symbol 5 is formed with a plurality of points 7. A semiconductor wafer is cut down for each semiconductor pellet 3. The failure identifying symbol 5 of a semiconductor pellet 3 cut manually or through a proper device is recognized. For example, with use of an optical sensor the failure identifying symbol 5 is constructed into an L shape, and a pattern of the semiconductor device 3, any damage and any contamination of a mirror surface part of a peripheral part of the semiconductor wafer 1 are distinctly discriminated. Based upon the recognition of the failure identifying symbol 5 only good semiconductor devices 3 are extracted.



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